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# **MMVL3401T1G**

# **Silicon Pin Diode**

This device is designed primarily for VHF band switching applications but is also suitable for use in general-purpose switching circuits. Supplied in a Surface Mount package.

#### **Features**

- Rugged PIN Structure Coupled with Wirebond Construction for Optimum Reliability
- Low Capacitance: 0.7 pF Typ at  $V_R = 20 \text{ Vdc}$
- Very Low Series Resistance at 100 MHz:
   0.34 Ω (Typ) @ I<sub>F</sub> = 10 mAdc
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

#### **MAXIMUM RATINGS**

Rating	Symbol	Value	Unit
Continuous Reverse Voltage	V <sub>R</sub>	35	Vdc
Peak Forward Current	Ι <sub>Ε</sub>	20	mAdc

#### THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR5 Board, T <sub>A</sub> = 25°C (Note 1) Derate above 25°C	P <sub>D</sub>	200 1.57	mW mW/°C
Thermal Resistance Junction-to-Ambient	$R_{\theta JA}$	635	°C/W
Junction and Storage Temperature	T <sub>J</sub> , T <sub>stg</sub>	150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR4 Minimum Pad



# ON Semiconductor®

http://onsemi.com

# SILICON PIN SWITCHING DIODE





SOD-323 CASE 477 STYLE 1

#### **MARKING DIAGRAM**



4D = Device Code M = Date Code\* ■ = Pb-Free Package

(Note: Microdot may be in either location)
\*Date Code orientation may vary depending upon manufacturing location.

### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>		
MMVL3401T1G	SOD-323 (Pb-Free)	3000 / Tape & Reel		

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

# MMVL3401T1G

# **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit
Reverse Breakdown Voltage (I <sub>R</sub> = 10 μAdc)	V <sub>(BR)R</sub>	35	_	-	Vdc
Diode Capacitance (V <sub>R</sub> = 20 Vdc)	C <sub>T</sub>	_	-	1.0	pF
Series Resistance (Figure 5) (I <sub>F</sub> = 10 mAdc, f = 100 MHz)	R <sub>S</sub>	-	-	0.7	Ω
Reverse Leakage Current (V <sub>R</sub> = 25 Vdc)	I <sub>R</sub>	-	_	0.1	μAdc

# **TYPICAL CHARACTERISTICS**

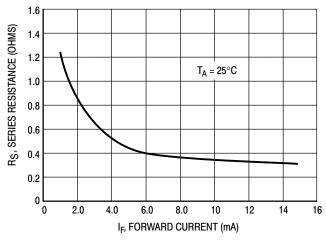
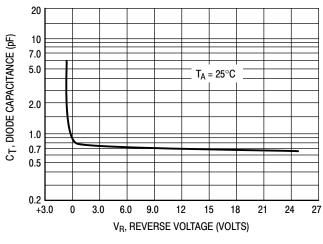


Figure 2. Forward Voltage

Figure 1. Series Resistance



100 40 I <sub>R</sub> , REVERSE CURRENT (μA) 10 4.0 V<sub>R</sub> = 25 Vdc 1.0 0.4 0.1 0.04 0.01 0.004 0.001 60 +100 +140 T<sub>A</sub>, AMBIENT TEMPERATURE (°C)

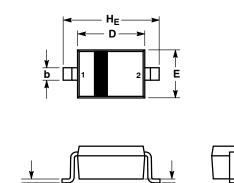
Figure 3. Diode Capacitance

Figure 4. Leakage Current

### MMVL3401T1G

# PACKAGE DIMENSIONS

SOD-323 CASE 477-02 **ISSUE H** 



NOTE 5

NOTE 3

# NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETERS. LEAD THICKNESS SPECIFIED PER L/F DRAWING WITH SOLDER PLATING.

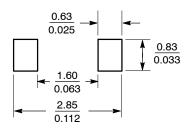
  4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

  5. DIMENSION L IS MEASURED FROM END OF RADIUS.

	MILLIMETERS			INCHES			
DIM	MIN	NOM	MAX	MIN	NOM	MAX	
Α	0.80	0.90	1.00	0.031	0.035	0.040	
A1	0.00	0.05	0.10	0.000	0.002	0.004	
A3	0.15 REF			0.006 REF			
b	0.25	0.32	0.4	0.010	0.012	0.016	
С	0.089	0.12	0.177	0.003	0.005	0.007	
D	1.60	1.70	1.80	0.062	0.066	0.070	
E	1.15	1.25	1.35	0.045	0.049	0.053	
L	0.08			0.003			
HE	2.30	2.50	2.70	0.090	0.098	0.105	

STYLE 1: PIN 1. CATHODE 2. ANODE

# **SOLDERING FOOTPRINT\***



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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